

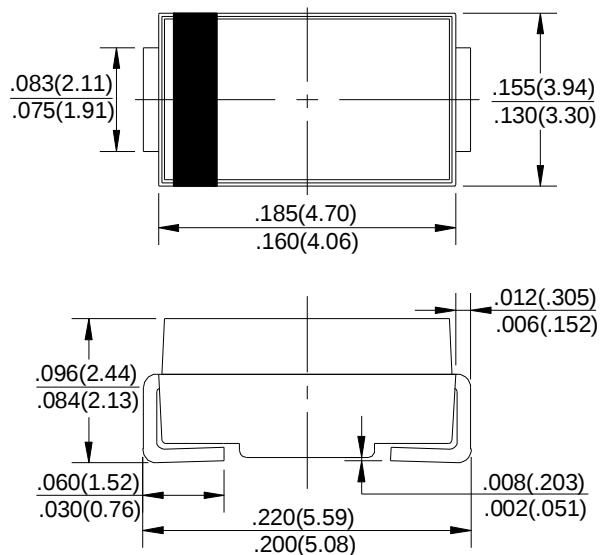
CURRENT 5.0 Ampere
VOLTAGE RANG 20 to 150 Volts

SS52L THRU SS515L

Features

- Low profile package
- Ideal for automated placement
- Ultrafast reverse recovery time
- Low power losses, high efficiency
- Low forward voltage drop
- High surge capability
- High temperature soldering:
260°C/10 seconds at terminals
- Component in accordance to

DO-214AA (SMB)



Dimensions in inches and (millimeters)

Mechanical Date

- **Case:** JEDEC DO-214AA (SMB) molded plastic
- **Terminals:** Solder plated, solderable per J-STD-002B and JESD22-B102D
- **Polarity:** Laser band denotes cathode end

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25°C ambient temperature unless otherwise specified.

Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

		SS52L	SS53L	SS54L	SS55L	SS56L	SS58L	SS510L	SS515L	UNITS
Maximum recurrent peak reverse voltage	V _{RRM}	20	30	40	50	60	80	100	150	V
Maximum RMS voltage	V _{RWS}	14	21	28	35	42	56	70	105	V
Maximum DC blocking voltage	V _{DC}	20	30	40	50	60	80	100	150	V
Maximum average forw ord rectified current at T _L (SEE FIG.1) (NOTE 2)	I _(AV)	5.0								A
Peak forw ard surge current 8.3ms single half-sine-w ave superimposed on rated load(JEDEC Method)	I _{FSM}	150								A
Maximum instantaneous forw ard voltage at 5.0A(NOTE.1)	V _F	0.45			0.56		0.75			V
Maximum DC reverse current @T _A =25°C at rated DC blockjing voltage(NOTE1) @T _A =100°C	I _R	0.5								mA
		20					10			
Typical thermal resitance (NOTE2)	R _{θJA}	55								°C/W
	R _{θJL}	17								
Operating junction temperature range	T _J	-55--- +150								°C
Storage temperature range	T _{STG}	-55--- +150								°C

Note: 1. Measured at 1MHz and applied reverse voltage of 4.0V D.C.
2. P.C.B. mounted with 0.2x0.2" (5.0x5.0mm) copper pad areas

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Characteristic Curves ($T_A=25^\circ\text{C}$ unless otherwise noted)

FIG.1 – FORWARD DERATING CURVE

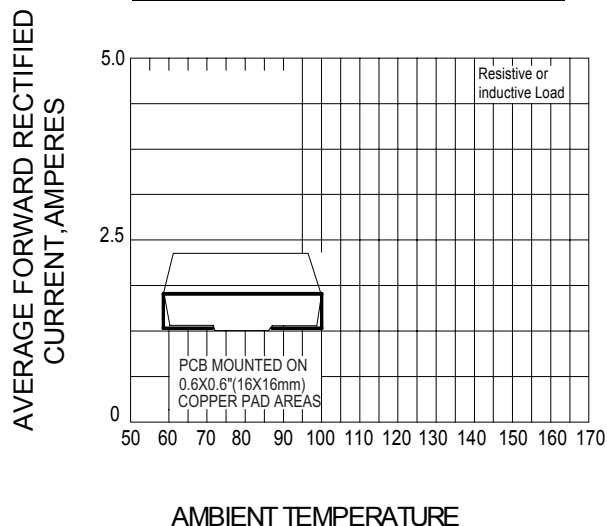


FIG.2– PEAK FORWARD SURGE CURRENT

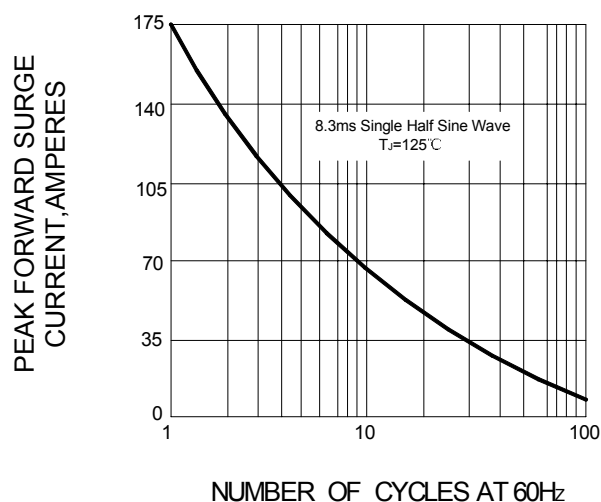


FIG.3 – TYPICAL FORWARD CHARACTERISTICS

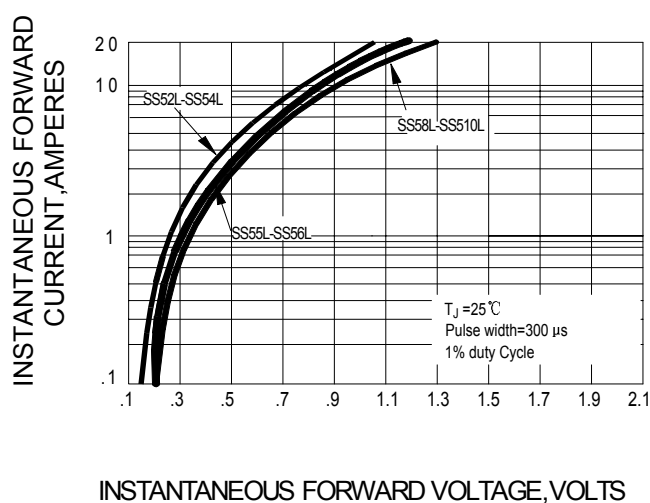
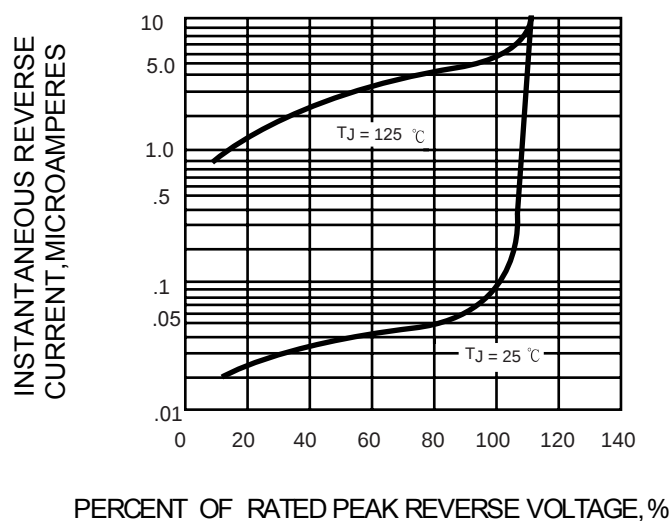


FIG.4 – TYPICAL REVERSE CHARACTERISTICS



SMA PAD LAYOUT

